参与 2023 国 名 公

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| | MEMS | | | | | | | |
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| | 1<br>2<br>3<br>4<br>5<br>6 | | | | | | | |
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| | | | | | | | | |
| | 1 | | ZL201010181105.3 | 2013 02 13 | 1135038 | | | |
| | 2 | | ZL201210514737.6 | 2015 09 16 | 1787120 | | | |
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| | | | ZL20091019 | 2012 07 18 | 100514 | | | |

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| | 3 | | 6795.7 | | 0 | | | |
| | 111<br>2 | | ZL201<br>31002<br>8123.1 | 2015<br>08 05 | 174579<br>6 | | | |
| | SOI<br>MEMS<br>1 | | ZL201<br>41019<br>1944.1 | 2016<br>04 06 | 201609<br>2 | | | |
| | 3 | | ZL200<br>81003<br>7306.9 | 2010<br>02 03 | 597434 | | | |
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| | MEMS<br>3 | | ZL201<br>31001<br>2777.5 | 2015<br>09 23 | 179521<br>1 | | | |
| | Semiconductor devices - Micro-electromechanical devices - Part 25: Silicon based MEMS fabrication technology - Measurement method of pull-press and shearing strength of micro bonding area | | IEC<br>62047<br>-25 | 2016<br>9 1 | / | | | |